

# 2SD1478A

## Silicon NPN epitaxial planar type darlington

For low frequency amplification

**■ Features**

- Forward current transfer ratio  $h_{FE}$  is designed high, which is appropriate to the driver circuit of motors and printer hammer.
- A shunt resistor is omitted from the driver.

**■ Absolute Maximum Ratings**  $T_a = 25^\circ\text{C}$

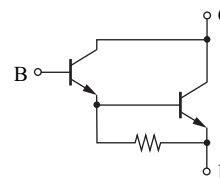
| Parameter                             | Symbol    | Rating      | Unit             |
|---------------------------------------|-----------|-------------|------------------|
| Collector-base voltage (Emitter open) | $V_{CBO}$ | 60          | V                |
| Collector-emitter voltage (Base open) | $V_{CEO}$ | 50          | V                |
| Emitter-base voltage (Collector open) | $V_{EBO}$ | 5           | V                |
| Collector current                     | $I_C$     | 500         | mA               |
| Peak collector current                | $I_{CP}$  | 750         | mA               |
| Collector power dissipation           | $P_C$     | 200         | mW               |
| Junction temperature                  | $T_j$     | 150         | $^\circ\text{C}$ |
| Storage temperature                   | $T_{stg}$ | -55 to +150 | $^\circ\text{C}$ |

**■ Package**

- Code  
Mini3-G1
- Pin Name  
1: Base  
2: Emitter  
3: Collector

**■ Marking Symbol: 2O**

**■ Internal Connection**



**■ Electrical Characteristics**  $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

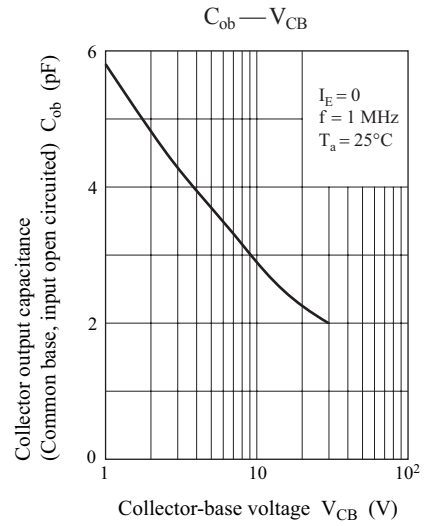
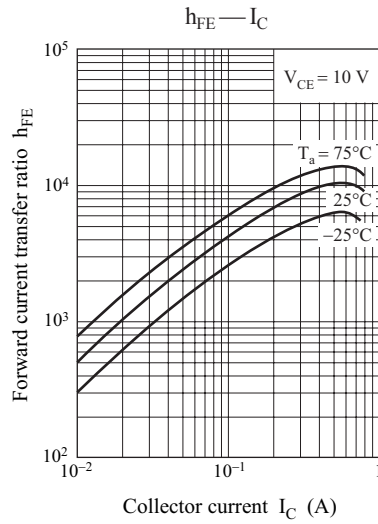
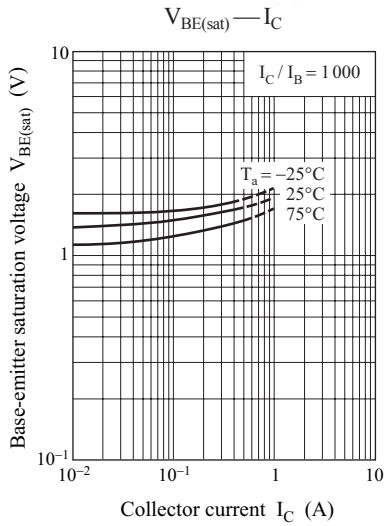
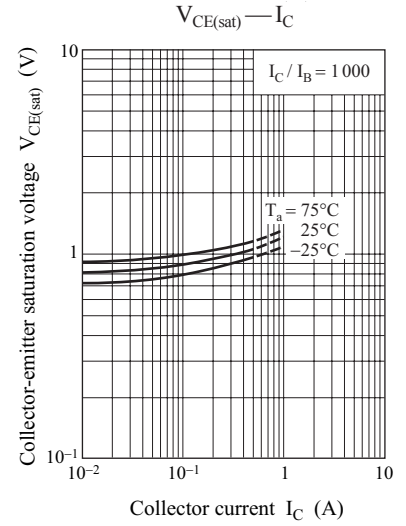
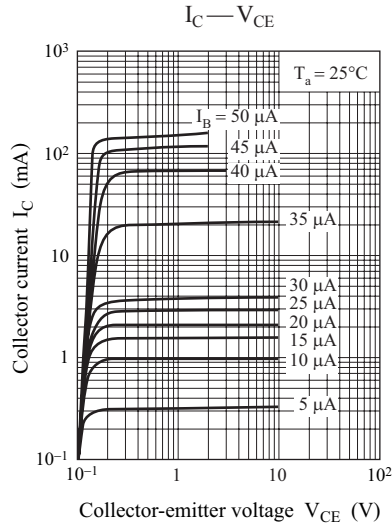
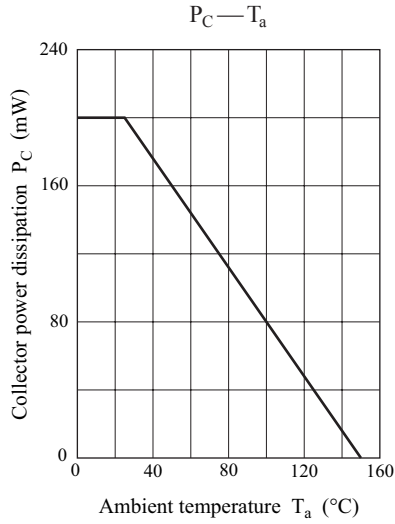
| Parameter                                    | Symbol        | Conditions   | Min  | Typ | Max   | Unit |
|--|---------------|--|------|-----|-------|------|
| Collector-base voltage (Emitter open)        | $V_{CBO}$     | $I_C = 100 \mu\text{A}, I_E = 0$                                   | 60   |     |       | V    |
| Collector-emitter voltage (Base open)        | $V_{CEO}$     | $I_C = 1 \text{ mA}, I_B = 0$                                      | 50   |     |       | V    |
| Emitter-base voltage (Collector open)        | $V_{EBO}$     | $I_E = 100 \mu\text{A}, I_C = 0$                                   | 5    |     |       | V    |
| Collector-base cutoff current (Emitter open) | $I_{CBO}$     | $V_{CB} = 25 \text{ V}, I_E = 0$                                   |      |     | 100   | nA   |
| Emitter-base cutoff current (Collector open) | $I_{EBO}$     | $V_{EB} = 4 \text{ V}, I_C = 0$                                    |      |     | 100   | nA   |
| Forward current transfer ratio *1, *2        | $h_{FE}$      | $V_{CE} = 10 \text{ V}, I_C = 500 \text{ mA}$                      | 4000 |     | 20000 | —    |
| Collector-emitter saturation voltage *1      | $V_{CE(sat)}$ | $I_C = 500 \text{ mA}, I_B = 0.5 \text{ mA}$                       |      |     | 2.5   | V    |
| Base-emitter saturation voltage *1           | $V_{BE(sat)}$ | $I_C = 500 \text{ mA}, I_B = 0.5 \text{ mA}$                       |      |     | 3.0   | V    |
| Transition frequency                         | $f_T$         | $V_{CB} = 10 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$ |      | 200 |       | MHz  |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. \*1: Pulse measurement

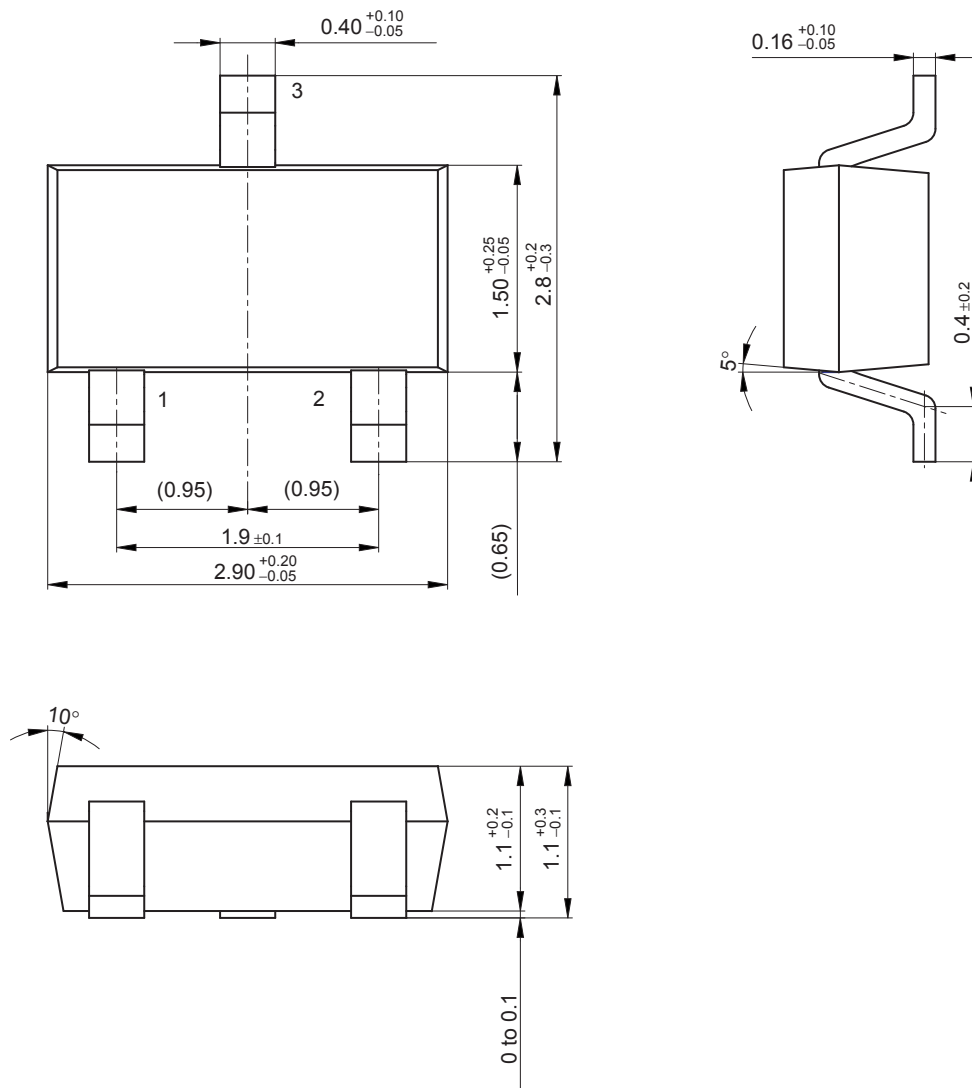
\*2: Rank classification

| Rank     | Q             | R             |
|----------|---------------|---------------|
| $h_{FE}$ | 4000 to 10000 | 8000 to 20000 |



Mini3-G1

Unit: mm



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